# XN01215 (XN1215)

## Silicon NPN epitaxial planar type

### For switching/digital circuits

#### ■ Features

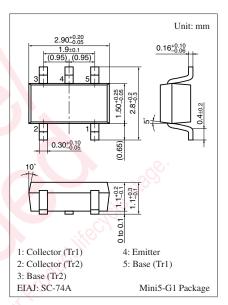
- Two elements incorporated into one package (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

#### ■ Basic Part Number

• UNR2215 (UN2215) × 2

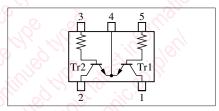
### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | $V_{CBO}$        | 50          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 50          | V    |  |
| Collector current                     | $I_{C}$          | 100         | mA   |  |
| Total power dissipation               | $P_{T}$          | 300         | mW   |  |
| Junction temperature                  | $T_{j}$          | 150         | °C . |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +150 | °C   |  |



Marking Symbol: 9M

#### Internal Connection



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

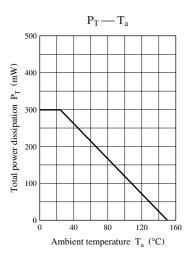
| Parameter                                    | Symbol                | Conditions   | Min  | Тур  | Max  | Unit |
|--|-----------------------|--|------|------|------|------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$             | $I_C = 10 \mu\text{A}, I_E = 0$  | 50   |      |      | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>      | $I_C = 2 \text{ mA}, I_B = 0$  | 50   |      |      | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$             | $V_{CB} = 50 \text{ V}, I_{E} = 0$                                       |      |      | 0.1  | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>      | $V_{CE} = 50 \text{ V}, I_{B} = 0$                                       |      |      | 0.5  | μΑ   |
| Emitter-base cutoff current (Collector open) | I <sub>EBO</sub>      | $V_{EB} = 6 \text{ V}, I_{C} = 0$  |      |      | 0.01 | mA   |
| Forward current transfer ratio               | h <sub>FE</sub>       | $V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$                            | 160  |      | 460  | _    |
| h <sub>FE</sub> Ratio *                      | h <sub>FE(Small</sub> | $V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$                            | 0.50 | 0.99 |      |      |
|  | /Large)               | 0/0  |      |      |      |      |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub>  | $I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$                              |      |      | 0.25 | V    |
| Output voltage high-level                    | V <sub>OH</sub>       | $V_{CC} = 5 \text{ V}, V_B = 0.5 \text{ V}, R_L = 1 \text{ k}\Omega$     | 4.9  |      |      | V    |
| Output voltage low-level                     | V <sub>OL</sub>       | $V_{CC} = 5 \text{ V}, V_{B} = 2.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$ |      |      | 0.2  | V    |
| Input resistance                             | R <sub>1</sub>        |  | -30% | 10   | +30% | kΩ   |
| Transition frequency                         | $f_T$                 | $V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$        |      | 150  |      | MHz  |

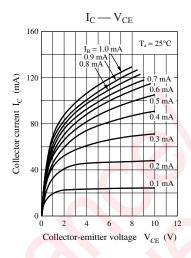
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

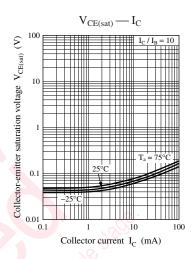
2. \*: Ratio between 2 elements

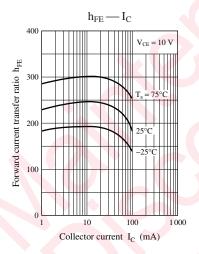
Note) The part number in the parenthesis shows conventional part number.

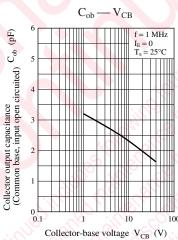
## **Panasonic**

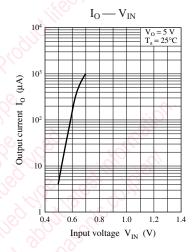


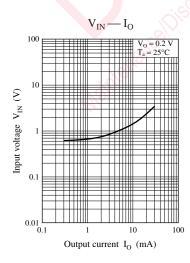












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